## N-Channel Enhancement Mode MOSFET

### Features

- Low RDS( ON )
- Low Miller Charge
- Halogen and Antimony Free(HAF), RoHS compliant

### Application

- Motor/Body Load Control
- Load Switch
- DC-DC converters and Off-line UPS

### **Key Parameters**

Parameter	Value	Unit	
BV <sub>DSS</sub>	30	V	
D Max	3.1 @ V <sub>GS</sub> = 10 V	mΩ	
R <sub>DS(ON)</sub> Max	4.2 @ V <sub>GS</sub> = 4.5 V	mΩ	
V <sub>GS(th)</sub> typ	1.5	V	
Q <sub>g</sub> typ	79 @ V <sub>GS</sub> = 10 V	nC	

#### Absolute Maximum Ratings (at Ta = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	V	
Continuous Drain Current	lo	68 43	А	
Peak Drain Current, Pulsed <sup>1)</sup>	I <sub>DM</sub>	210	A	
Avalanche Current	I <sub>AS</sub>	40	А	
Single Pulse Avalanche Energy 2)	Eas	80	mJ	
Power Dissipation	T <sub>c</sub> = 25°C T <sub>c</sub> = 100°C	PD	34.7 13.8	W
Operating Junction and Storage Tempera	TJ, Tstg	- 55 to + 150	°C	

### **Thermal Characteristics**

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Case	Rejc	3.6	°C/W
Thermal Resistance from Junction to Ambient <sup>3)</sup>	Reja	50	°C/W

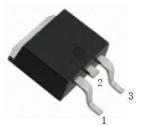
<sup>1)</sup> Pulse Test: Pulse Width  $\leq$  100 µs, Duty Cycle  $\leq$  2%, Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub> = 150°C.

<sup>2)</sup> Limited by  $T_{J(MAX)}$ , starting  $T_J = 25 \text{ °C}$ , L = 0.1 mH,  $R_g = 25 \Omega$ ,  $I_D = 40 \text{ A}$ ,  $V_{GS} = 10 \text{ V}$ .

<sup>3)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.



Drain Gate



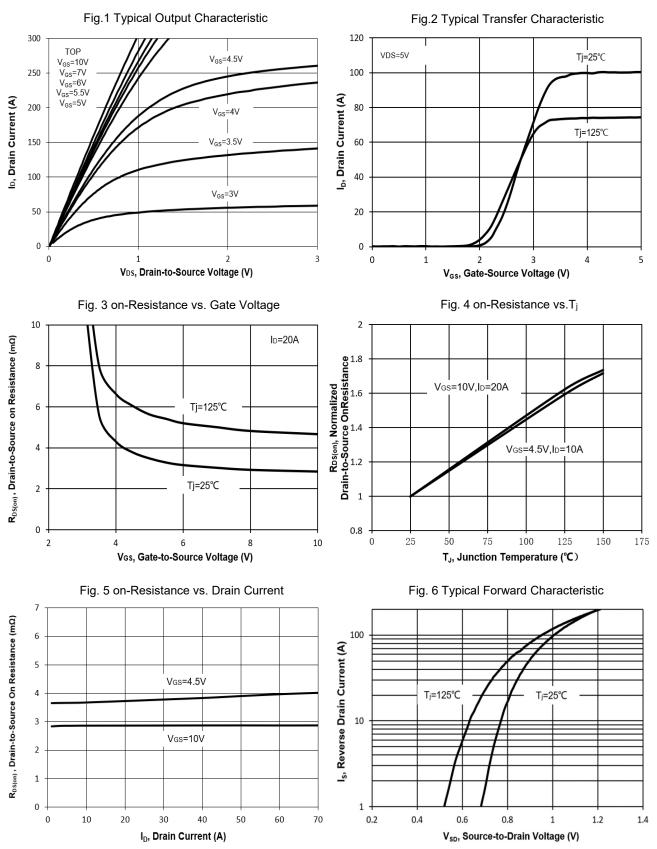
1.Gate 2.Drain 3.Source TO-252 Plastic Package

### Characteristics at Ta = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS			1	1	
Drain-Source Breakdown Voltage at $I_D = 250 \ \mu A$	BV <sub>DSS</sub>	30	-	-	V
Drain-Source Leakage Current at V <sub>DS</sub> = 24 V	IDSS	-	-	1	μA
Gate Leakage Current at $V_{GS}$ = ± 20 V	lgss	-	-	± 100	nA
Gate-Source Threshold Voltage at V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 µA	V <sub>GS(th)</sub>	1.2	-	2.5	V
Drain-Source On-State Resistance at $V_{GS}$ = 10 V, $I_D$ = 20 A at $V_{GS}$ = 4.5 V, $I_D$ = 10 A	R <sub>DS(on)</sub>	-	2.4	3.1 4.2	mΩ
DYNAMIC PARAMETERS					
Gate resistance at $V_{DS}$ = 0 V, f = 1 MHz	Rg	-	0.6	-	Ω
Forward Transconductance at $V_{DS}$ = 5 V, $I_D$ = 20 A	<b>g</b> fs	-	38	-	S
Input Capacitance at $V_{GS}$ = 0 V, $V_{DS}$ = 15 V, f = 1 MHz	C <sub>iss</sub>	-	3652	-	pF
Output Capacitance at $V_{GS}$ = 0 V, $V_{DS}$ = 15 V, f = 1 MHz	Coss	-	430	-	pF
Reverse Transfer Capacitance at $V_{GS}$ = 0 V, $V_{DS}$ = 15 V, f = 1 MHz	Crss	-	353	-	pF
Gate charge total at $V_{DS}$ = 15 V, $I_D$ = 20 A, $V_{GS}$ = 10 V at $V_{DS}$ = 15 V, $I_D$ = 20 A, $V_{GS}$ = 4.5 V	Qg	-	79 40	-	nC
Gate to Source Charge at $V_{DS}$ = 15 V, $I_D$ = 20 A, $V_{GS}$ = 10 V	Qgs	-	9.5	-	nC
Gate to Drain Charge at $V_{DS}$ = 15 V, $I_D$ = 20 A, $V_{GS}$ = 10 V	Q <sub>gd</sub>	-	20	-	nC
Turn-On Delay Time at V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A, R <sub>g</sub> = $3.3 \Omega$	t <sub>d(on)</sub>	-	25.6	-	nS
Turn-On Rise Time at V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A, R <sub>g</sub> = 3.3 $\Omega$	tr	-	35	-	nS
Turn-Off Delay Time at V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A, R <sub>g</sub> = 3.3 $\Omega$	$t_{d(off)}$	-	25	-	nS
Turn-Off Fall Time at V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A, R <sub>g</sub> = $3.3 \Omega$	t <sub>f</sub>	-	4.8	-	nS
Body-Diode PARAMETERS			i .	i	
Drain-Source Diode Forward Voltage at Is = 1 A, V <sub>GS</sub> = 0 V	V <sub>SD</sub>	-	0.7	1.2	V
Body-Diode Continuous Current	ls	-	-	68	Α
Body-Diode Continuous Current, Pulsed	lsм	-	-	210	Α
Body Diode Reverse Recovery Time at I <sub>S</sub> = 10 A, di/dt = 100 A / μs	t <sub>rr</sub>	-	17	-	nS
Body Diode Reverse Recovery Charge at $I_S = 10 \text{ A}$ , di/dt = 100 A / $\mu$ s	Qrr	-	7.5	-	nC



#### **Electrical Characteristics Curves**

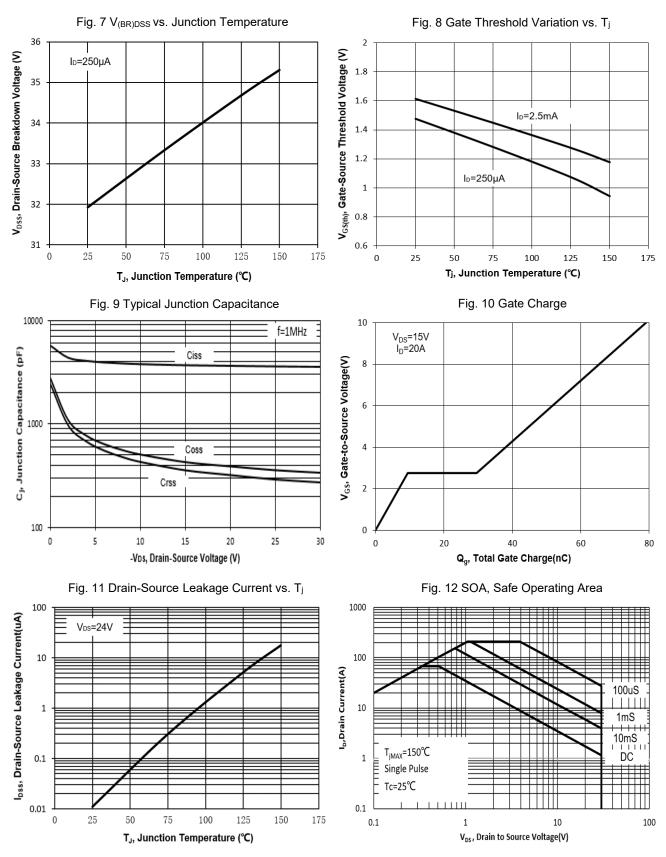




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#### **Electrical Characteristics Curves**





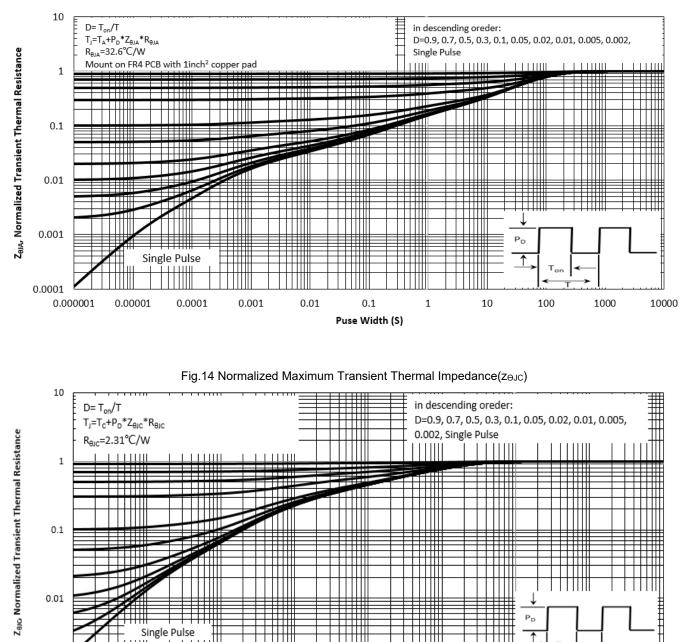
0.001 0.000001

0.00001

0.0001

0.001

### **Electrical Characteristics Curves**



#### Fig.13 Normalized Maximum Transient Thermal Impedance(z<sub>OJA</sub>)

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1 т

10

100

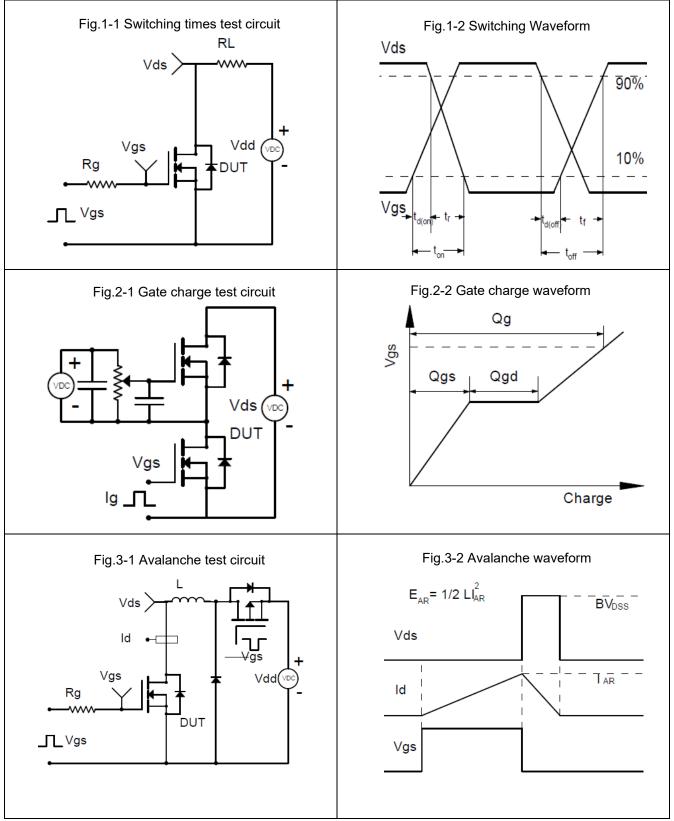
1

0.01

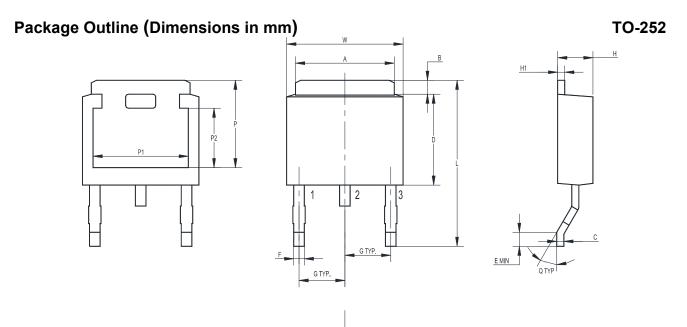
Puse Width(S)

0.1

#### **Test Circuits**

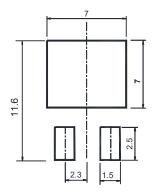







UNIT	Α	В	С	D	Е	F	G	W	Н	H1	Q	L	Р	P1	P2
	5.5	1.20	0.65	6.2	0.8	1.0	2.3	6.7	2.5	0.65	60°	10.7	5.4	5.0	3.4
mm	4.9	0.85	0.4	5.6	MIN	0.5	TYP	6.1	2.1	0.4	TYP	9	5.0	4.6	2.9

## **Recommended Soldering Footprint**



## **Packing information**

Dookaga	Package Tape Width (mm)		tch	Reel	Size	Per Reel Packing Quantity	
гаскауе			inch	mm	inch	Fer Reel Facking Quantity	
TO-252	12	8 ± 0.1	0.315 ± 0.004	330	13	2,500	

## Marking information

- " TR03N030LS " = Part No.
- " \*\*\*\*\*\* " = Date Code Marking

Font type: Arial





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